

COMPLIANT

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

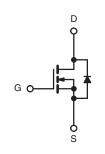
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
30	0.00275 at V _{GS} = 10 V	39	30 nC			
30	0.0034 at V_{GS} = 4.5 V	35	30110			



- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Low-Side DC/DC Conversion
 - Notebook
 - Gaming



SO-8 S D 8 1 S D 7 2 S D 3 6 D G 5 4 Top View

Ordering Information: Si4126DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		39		
Continuous Drain Current ($T_{I} = 150 \ ^{\circ}C$)	T _C = 70 °C		31		
Continuous Drain Current (1j = 150°C)	T _A = 25 °C		26.5 ^{b, c}		
	T _A = 70 °C	1	21 ^{b, c}	•	
Pulsed Drain Current		I _{DM}	70	A	
Continuous Source-Drain Diode Current	T _C = 25 °C	1-	7.0		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.1 ^{b, c}		
Single Pulse Avalanche Current		I _{AS}	40		
Avalanche Energy	nche Energy $L = 0.1 \text{ mH}$		80	mJ	
	T _C = 25 °C		7.8		
Movimum Dower Dissinction	T _C = 70 °C	P _D	5.0	w	
Maximum Power Dissipation	T _A = 25 °C		3.5 ^{b, c}	vv	
	T _A = 70 °C	1 [2.2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	29	35	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	13	16	0/10		

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 80 °C/W.



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050		24		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- Ι _D = 250 μΑ		- 6.4			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	30			Α	
		V _{GS} = 10 V, I _D = 15 A		0.0022	0.00275		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		0.0027	0.0034	Ω 1	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			4405		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		760			
Reverse Transfer Capacitance	C _{rss}	1		285			
Total Gate Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		70	105		
	Q _g			30	45	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		10.2			
Gate-Drain Charge	Q _{gd}			7.4			
Gate Resistance	Rg	f = 1 MHz	0.3	1.4	2.8	Ω	
Turn-On Delay Time	t _{d(on)}			36	60		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		20	40		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 10 A, V_GEN = 4.5 V, R_g = 1 Ω		53	90		
Fall Time	t _f			24	40		
Turn-On Delay Time	t _{d(on)}			15	30	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_{D}\cong$ 10 A, V_{GEN} = 10 V, R_{g} = 1 Ω		43	70		
Fall Time	t _f			10	20		
Drain-Source Body Diode Characterist	cs						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			7.0	^	
Pulse Diode Forward Current ^a	I _{SM}				70	A	
Body Diode Voltage	V _{SD}	I _S = 3 A		0.71	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			38	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C		38	60	nC	
Reverse Recovery Fall Time	t _a	f = 10 A, and = 100 A/		19			
Reverse Recovery Rise Time	t _b	\neg		20		ns	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



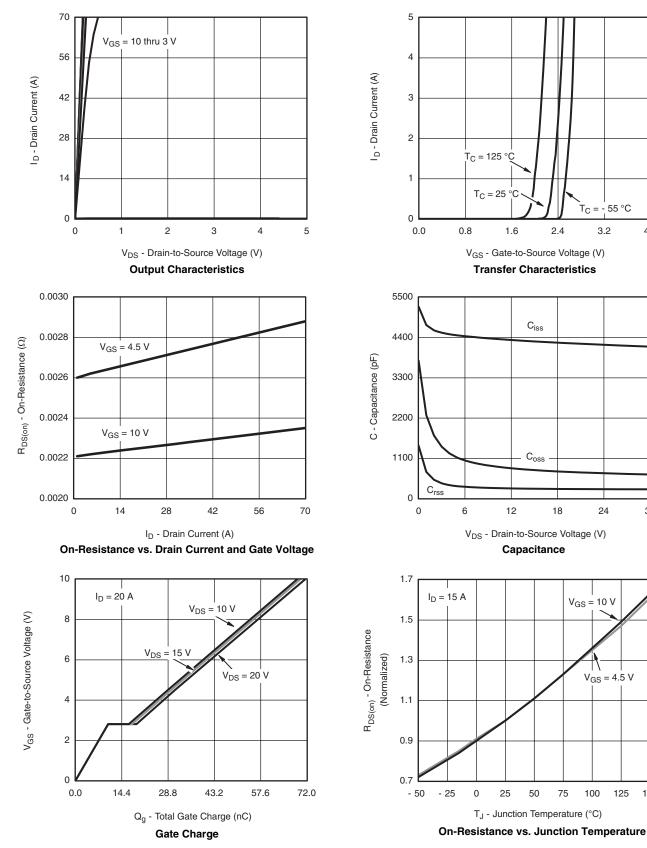


4.0

30

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Document Number: 69994 S-80895-Rev. B, 21-Apr-08 150

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 $I_{\rm D} = 15 \; {\rm A}$

T_J = 125 °C

T_J = 25 °C

8

10

10

4

6

1

0.1

Time (s)

1 s 10 s

DC

100

BVDSS

10

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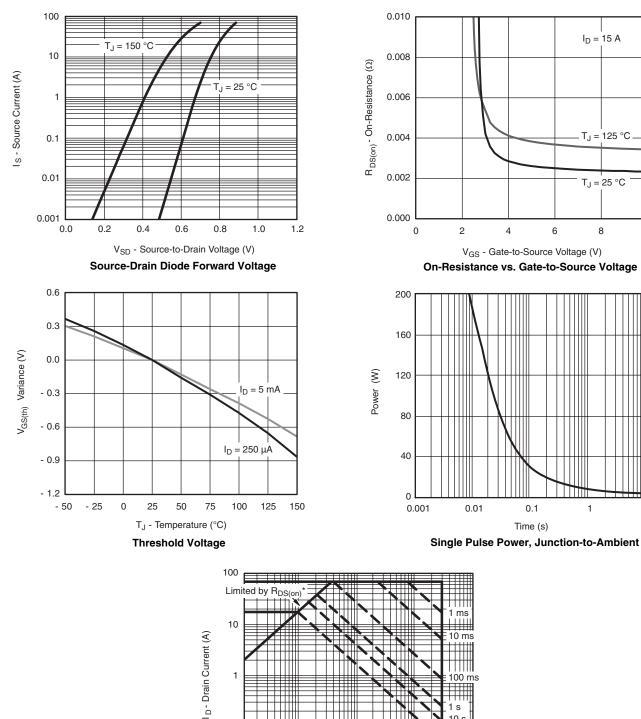
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V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Safe Operating Area, Junction-to-Ambient

T_A = 25 °C Single Pulse

0.1

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



0.1

0.01

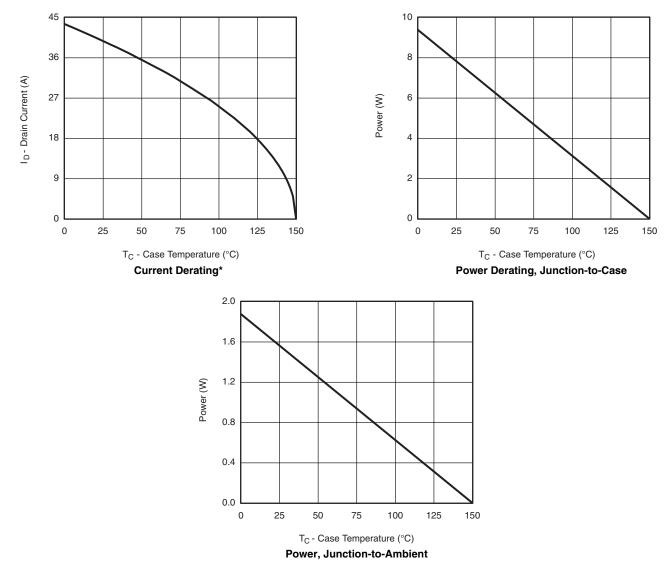
0.01





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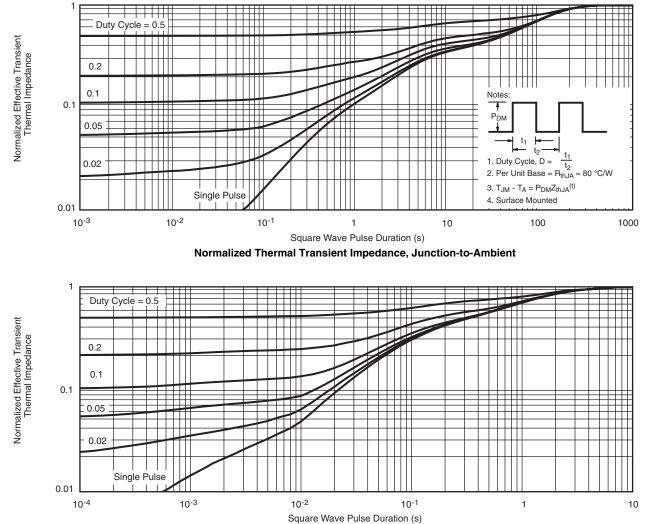


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?69994.



Package Information

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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